

10/066123

UNITED STATES PATENT AND TRADEMARK OFFICE  
**CERTIFICATE OF CORRECTION**

PATENT NO. : 6,819,117 B2  
DATED : November 16, 2004  
INVENTOR(S) : Kenneth R. Wilsher

Page 1 of 2

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Title page,

Item [56], **References Cited**, U.S. PATENT DOCUMENTS, insert the following:

- 5,940,545      08/1999              Kash et al. --
- 6,028,952      02/2000              Kash et al. --
- 6,172,512      01/2001              Evans et al. --
- 6,304,668      10/2001              Evans et al. --

OTHER PUBLICATIONS, insert the following:

- J. Bude, *Hot-carrier luminescence in Si*, PHYS. REV. B, 45(11), 15 March 1992, pages 5848-5856 --
- S. Villa et al., *Photon emission from hot electrons in silicon*, PHYS. REV. B, 52 (15), 15 October 1995-I, pages 10993-10999 --
- J. Kash et al., *Full Chip Optical Imaging of Logic State Evolution in CMOS Circuits*, IEDM 96 Late News Paper (1996) 1, pages 934-936 --
- D. Knebel et al., *Diagnosis and Characterization of Timing-Related Defects by Time-Dependent Light Emission*, ITC PROCEEDINGS 1998 --
- M. Bruce et al., *Waveform Acquisition from the Backside of Silicon Using Electra-Optic Probing*, PROCEEDINGS FROM THE 25<sup>th</sup> INTERNATIONAL SYMPOSIUM FOR TESTING AND FAILURE ANALYSIS, 14-18 November 1999, pages 19-25 --
- T. Eiles et al., *Optical Probing of VLSI IC's from the Silicon Backside*, PROCEEDINGS FROM THE 25<sup>TH</sup> INTERNATIONAL SYMPOSIUM FOR TESTING AND FAILURE ANALYSIS, 14-18 November 1999, pages 27-33--
- M. McManus, *Picosecond Imaging Circuit Analysis of the IBM G6 Microprocessor Cache*, PROCEEDINGS FROM THE 25<sup>TH</sup> INTERNATIONAL SYMPOSIUM FOR TESTING AND FAILURE ANALYSIS, 14-18 November 1999, pages 35-38 --
- N. Goldblatt et al., *Unique and Practical IC Timing Analysis Tool Utilizing Intrinsic Photon Emission*, MICROELECTRONICS RELIABILITY 41 (2001) 1507-1512 --
- G. Dajee et al., *Practical, Non-Invasive Optical Probing for Flip-Chip Devices*, ITC Paper 15.3 (Baltimore, October 28 – November 2, 2001) 433-442 --
- IDS® PICA, *Advanced Optical Imaging for Analysis of 0.13-micron and SOI Devices*, Schlumberger Semiconductor Solutions brochure printed 3/01, four pages --

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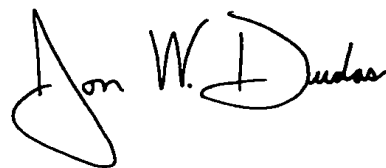
It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Title page, (cont.)

-- FOREIGN PATENT DOCUMENTS 0 937 989 A2 08/1999 EPO --

Signed and Sealed this

Nineteenth Day of April, 2005

A handwritten signature in black ink, reading "Jon W. Dudas". The signature is stylized, with a large loop for the "J" and a cursive "Dudas".

JON W. DUDAS  
*Director of the United States Patent and Trademark Office*